No.	Ite	em	Specifications	Test Method			
1	Operating Temperatu	ıre Range	−55 to +125°C				
2	Appearar	ice	No defects or abnormalities	Visual inspection			
3	Dimensio	ns	Within the specified dimension	Using calipers			
4	Dielectric Strength		No defects or abnormalities	No failure should be observed when voltage in Table is applied between the terminations for 1 to 5 sec., provided the charge/ discharge current is less than 50mA.    Rated voltage   Test voltage			
5	Insulation F	Resistance	More than 10,000M $\Omega$	The insulation resistance should be measured with DC500±50V (DC250±25V in case of rated voltage: DC250V) and within 60±5 sec. of charging.			
6	Capacitance		Within the specified tolerance	The capacitance/Q should be measured at the frequency and			
7	Q		U2J char. : 1,000 min. SL char. : 400+20C*1 min.	Capacitance         Frequency         Voltage           C<1,000pF         1±0.2MHz         AC0.5 to 5V(r.m.s.)           C≥1,000pF         1±0.2kHz         AC1±0.2V(r.m.s.)			
8	Capacitance Temperature Characteristics		Temp. Coefficient U2J char.:  —750±120 ppm/°C (Temp. Range: +25 to +125°C)  —750+120, —347 ppm/°C (Temp. Range: —55 to +25°C) SL char.:  +350 to −1000 ppm/°C (Temp. Range: +20 to +85°C)	The capacitance measurement should be made at each step specified in Table.    Step   Temperature (°C)     1   25±2 (20±2 for SL char.)     2   Min. Operating Temp.±3     3   25±2 (20±2 for SL char.)     4   Max. Operating Temp.±2     5   25±2 (20±2 for SL char.)     SL char. :   The capacitance should be measured at even 85℃ between step 3 and step 4.			
9	Adhesive Strength of Termination		No removal of the terminations or other defect should occur.	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 1.  Then apply 10N force in the direction of the arrow.  The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.    10N, 10±1s   Glass Epoxy Board   Glass Epoxy Board			
		Appearance	No defects or abnormalities	Solder the capacitor to the test jig (glass epoxy board).  The capacitor should be subjected to a simple harmonic motion having a total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55Hz. The frequency range, from 10 to 55Hz and return to 10Hz, should be traversed in approximately 1 min. This motion should be applied for a period of 2 hrs. in each of 3 mutually perpendicular directions (total of 6 hrs.).  Solder resist  Cu  Glass Epoxy Board			
10		Capacitance	Within the specified tolerance				
	Vibration Resistance	Q	U2J char. : 1,000 min. SL char. : 400+20C*1 min.				

<sup>\*1 &</sup>quot;C" expresses nominal capacitance value (pF).

Continued on the following page.



No.	Ite	Item Specifications					Test Method				
11	Deflection		L×W (mm) 2.0×1.25 3.2×1.6 3.2×2.5 4.5×2.0	a 1.2 2.2 2.2 3.5	b   c   c   a   100	d occur.	d - 1.0	Solder the capacitor to the testing jig (glass epoxy board) shown in Fig. 2.  Then apply a force in the direction shown in Fig. 3.  The soldering should be done using the reflow method and should be conducted with care so that the soldering is uniform and free of defects such as heat shock.  20 50 Pressurizing speed: 1.0mm/s Pressurize  Pressurize  (in mm)  Fig. 3			
12	Solderab Terminati	-	Fig. 2  75% of the terminations are to be soldered evenly and continuously.					Immerse the capacitor in a solution of ethanol (JIS-K-8101) and rosin (JIS-K-5902) (25% rosin in weight proportion). Immerse in solder solution for 2±0.5 sec.  Immersing speed: 25±2.5mm/s  Temp. of solder: 245±5°C Lead Free Solder (Sn-3.0Ag-0.5Cu)  235±5°C H60A or H63A Eutectic Solder			
13	Resistance	Appearance	No marking defects  Within ±2.5%					Preheat the capacitor at 120 to 150°C* for 1 min.			
		Capacitance Change						Immerse the capacitor in solder solution at 260±5°C for 10±1 sec Let sit at room condition*1 for 24±2 hrs., then measure.  •Immersing speed: 25±2.5mm/s			
	to Soldering	Q	U2J char. : 1,000 min. SL char. : 400+20C* <sup>2</sup> min.					*Preheating fo	or more than 3.2×2.5mm		
	Heat	I.R.	More than $10,000 \text{M}\Omega$					Step	Temperature	Time	
		Dielectric Strength	In accordance with item No.4					1 2	100 to 120°C 170 to 200°C	1 min. 1 min.	
		Appearance	No marking def	ects				Fix the capaci	tor to the supporting jig (glass	epoxy board) shown	
	Temperature Cycle	Capacitance Change	Within ±2.5%					in Fig. 4.  Perform the 5 cycles according to the 4 heat treatments listed in the following table.			
		Q	U2J char. : 500 min. SL char. : 400+20C*² min.					Let sit for 24± Step	2 hrs. at room condition*1, the Temperature (°C)	en measure.  Time (min.)	
		I.R.	More than $10,000M\Omega$					1	Min. Operating Temp.±3	30±3	
14		Dielectric Strength	In accordance with item No.4					2 Room Temp. 2 to 3 3 Max. Operating Temp.±2 30±3 4 Room Temp. 2 to 3  4 Solder resist  Glass Epoxy Board  Fig. 4			
15	Humidity (Steady State)	Appearance	No marking def	ects							
		Capacitance Change	Within ±5.0%					Let the capacitor sit at 40±2°C and relative humidity of 90 to 95% for 500±26 hrs.  Remove and let sit for 24±2 hrs. at room condition*1, then measure.			
		Q	U2J char. : 350 min. SL char. : 275+5/2C* $^2$ min. More than 1,000M $\Omega$								
		I.R.									
		Dielectric Strength	In accordance with item No.4								
16	Life	Appearance	No marking def	ects							
		Capacitance Change	Within ±3.0%					Apply 120% of the rated voltage for 1,000 ±48 hrs. at maximum operating temperature ±3°C.			
		Q	U2J char. : 350 SL char. : 275+		١.			Remove and let sit for 24±2 hrs. at room condition*1, then			
		I.R.	More than 1,000MΩ  In accordance with item No.4					measure. The charge/discharge current is less than 50mA.			
		Dielectric Strength									
4				o- D : :	4 4 40	45 4 3561					

<sup>\*1 &</sup>quot;Room condition" Temperature: 15 to 35°C, Relative humidity: 45 to 75%, Atmospheric pressure: 86 to 106kPa \*2 "C" expresses nominal capacitance value (pF).